

This Sheet Has Been Replaced



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REPLACED

ABSTRACT

Process for encapsulating an electronic component, in particular an integrated circuit, with an encapsulating material, at least comprising the steps of:

- placing the component to be encapsulated in a cavity of a mould;
 - introducing the encapsulating material at elevated temperature into the cavity between the mould and the component to be encapsulated;
 - hardening the encapsulating material; and
 - releasing the encapsulated component from the cavity,
- the encapsulating material used comprising 40-65 % by weight of the engineering thermoplast and 60-35 % by weight of the reactive solvent.